

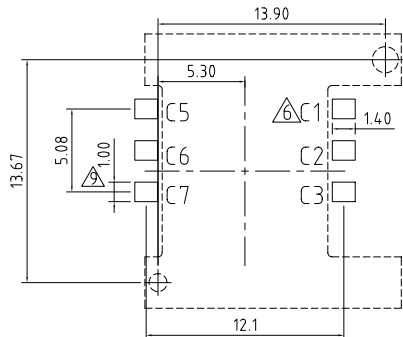
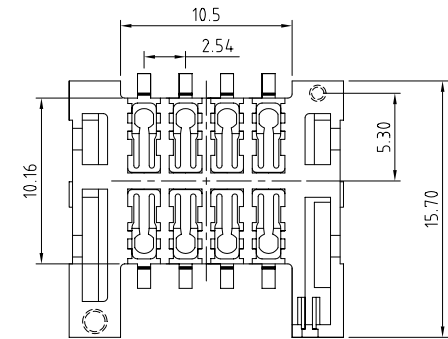
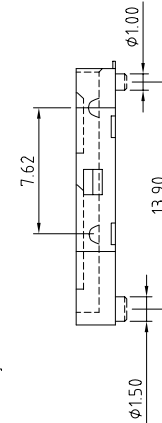
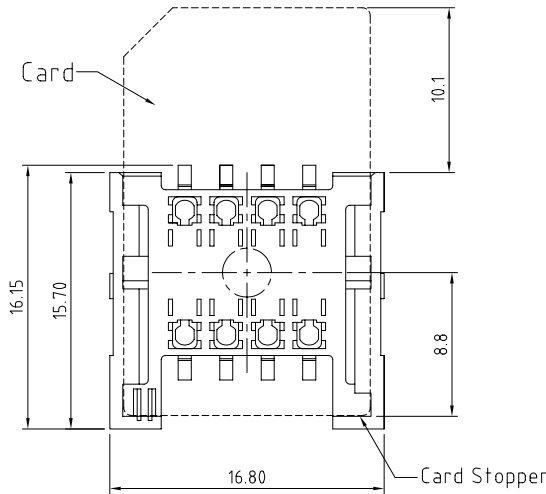
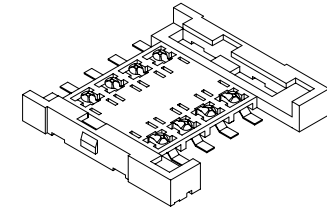
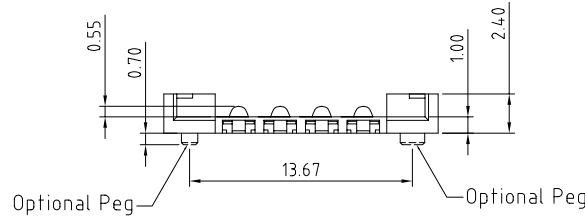
CH03-AA-B: SIM CARD CONNECTOR SMT, SLIDE IN TYPE, 6 OR 8 CONTACTS

FEATURES

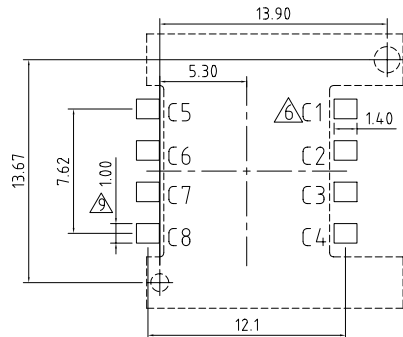
- GENERAL CHARACTERISTICS**  
 CONTACT PRINCIPLE: FRICTION TECHNOLOGY  
 MOUNTING SYSTEM: SMT TYPE  
 DURABILITY: 10,000 CYCLES MIN.
- MECHANICAL CHARACTERISTICS**  
 INSULATION MATERIAL: THERMOPLASTIC, UL 94V-0  
 CONTACT MATERIAL: PHOSPHOR BRONZE  
 CONTACT PLATING: GOLD OR PD OVER NICKEL
- ELECTRICAL CHARACTERISTICS**  
 CONTACT RESISTANCE: 50M OHMS TYPICAL, 100M OHMS MAX.  
 INSULATION RESISTANCE: > 1000M OHMS MIN. / 500V DC  
 RATED CURRENT: 0.5A MAX.  
 RATED VOLTAGE: 30V AC  
 WITHSTANDING DIELECTRIC VOLTAGE: 500V AC RMS FOR 1 MINUTE
- SOLDERABILITY**  
 VAPOR PHASE: 215°C FOR 30 SEC. MAX.  
 IR REFLOW: 260°C FOR 10 SEC.  
 MANUAL SOLDERING: 360°C FOR 3 SEC. MAX.
- ENVIRONMENTAL CHARACTERISTICS**  
 OPERATING TEMP.: -40°C~+85°C  
 OPERATING HUMIDITY: 10%~95% RH  
 STORAGE TEMP.: -40°C~+85°C  
 STORAGE HUMIDITY: 10%~95% RH  
 DAMP HEAT: 40°C, 90% RH, 500HR  
 SALT-MIST: 35°C, 5%, NaCl, 48H

NOTES:

- ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT.
- IF USING IN A HIGH TEMPERATURE ENVIRONMENT PLEASE CHECK WITH GRADCONN.



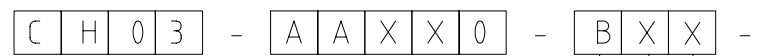
6 PINS VERSION



8 PINS VERSION

RECOMMENDED PCB LAYOUT

HOW TO ORDER



- NO. OF CONTACTS  
06 (STANDARD)  
OR  
08 (NON-STANDARD)
- WITHOUT SWITCH
- WITH OR WITHOUT LOCATING PEG  
A = WITH (STANDARD)  
B = WITHOUT (NON-STANDARD)
- PACKAGING OPTIONS  
T = TUBE   
R = REEL

<<NOTE : NON-STANDARD PARTS WOULD REQUIER HIGHER MOQ.>>

REV. DATE & DRN	10 21/02/04-CH-CH RELEASE
11 22/07/05-NYW	AMEND PACK OPTION
12 21/03/06-NYW	ADD ROHS OPTION
13 14/07/06-NYW	REMOVE NON-ROHS VERSION
14 20/05/07-NYW	ADD NOTES E.
15 22/08/11-NYW	ADD NOTES E.
16 24/06/07-NYW	AMEND PIN LAYOUT#
17 08/05/10-NYW	SEPERATE PCB LAYOUT, MARK STANDARD AND NON-STANDARD OPTION.
18 06/06/08-NYW	ADD ELECTRICAL SPEC
19 04/05/10-NYW	AMEND PCB PIN LAYOUT.

Scale: 3=1	THIRD ANGLE	Unstated Tolerances: 0 Dec Places 1 Dec Places 2 Dec Places 3 Dec Places	Material SEE NOTE
Drawn: CHC			
App'd: NYW	Title SIM CARD ACCEPTOR		NOT TO SCALE
Date: 4 MAY '10	Revision: 1.9		Unit: mm

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Type: CH03-AA
CH03-AA-B
Drawing Number:
Sheet 1 of 1
Drawing C  E and O E